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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	HCS12
Core Size	16-Bit
Speed	25MHz
Connectivity	I ² C, SCI, SPI
Peripherals	PWM, WDT
Number of I/O	59
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.25V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-QFP
Supplier Device Package	80-QFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s12a64cfue

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Table 0-2 Document References

User Guide	Version	Document Order Number
HCS12 CPU Reference Manual	V02	S12CPUV2/D
HCS12 Module Mapping Control (MMC) Block Guide	V04	S12MMCV4/D
HCS12 Multiplexed External Bus Interface (MEBI) Block Guide	V03	S12MEBIV3/D
HCS12 Interrupt (INT) Block Guide	V01	S12INTV1/D
HCS12 Background Debug (BDM) Block Guide	V04	S12BDMV4/D
HCS12 Breakpoint (BKP) Block Guide	V01	S12BKPV1/D
Clock and Reset Generator (CRG) Block User Guide	V04	S12CRGV4/D
Oscillator (OSC) Block User Guide	V02	S12OSCV2/D
Enhanced Capture Timer 16 Bit 8 Channel (ECT_16B8C) Block User Guide	V01	S12ECT16B8CV1/D
Analog to Digital Converter 10 Bit 8 Channel (ATD_10B8C) Block User Guide	V02	S12ATD10B8CV2/D
Inter IC Bus (IIC) Block User Guide	V02	S12IICV2/D
Asynchronous Serial Interface (SCI) Block User Guide	V02	S12SCIV2/D
Serial Peripheral Interface (SPI) Block User Guide	V02	S12SPIV2/D
Pulse Width Modulator 8 Bit 8 Channel (PWM_8B8C) Block User Guide	V01	S12PWM8B8CV1/D
64K Byte Flash (FTS64K) Block User Guide	V01	S12FTS64KV1/D
1K Byte EEPROM (EETS1K) Block User Guide	V01	S12EETS1KV1/D
Byte Level Data Link Controller -J1850 (BDLC) Block User Guide	V01	S12BDLCV1/D
Freescale Scalable CAN (MSCAN) Block User Guide	V02	S12MSCANV2/D
Voltage Regulator (VREG) Block User Guide	V01	S12VREGV1/D
Port Integration Module (PIM_9DJ64) Block User Guide	V01	S12PIM9DJ64V1/D

1.5.1 Detailed Register Map

\$0000 - \$000F

MEBI map 1 of 3 (HCS12 Multiplexed External Bus Interface)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0000	PORTA	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
\$0001	PORTB	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
\$0002	DDRA	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
\$0003	DDRB	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
\$0004	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0005	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0006	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0007	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0008	PORTE	Read:	Bit 7	6	5	4	3	2	Bit 1	Bit 0
		Write:								
\$0009	DDRE	Read:	Bit 7	6	5	4	3	Bit 2	0	0
		Write:								
\$000A	PEAR	Read:	NOACCE	0	PIPOE	NECLK	LSTRE	RDWE	0	0
		Write:								
\$000B	MODE	Read:	MODC	MODB	MODA	0	IVIS	0	EMK	EME
		Write:								
\$000C	PUCR	Read:	PUPKE	0	0	PUPEE	0	0	PUPBE	PUPAE
		Write:								
\$000D	RDRIV	Read:	RDPK	0	0	RDPE	0	0	RDPB	RDPA
		Write:								
\$000E	EBICTL	Read:	0	0	0	0	0	0	0	ESTR
		Write:								
\$000F	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

\$0010 - \$0014

MMC map 1 of 4 (HCS12 Module Mapping Control)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0010	INITRM	Read:	RAM15	RAM14	RAM13	RAM12	RAM11	0	0	RAMHAL
		Write:								
\$0011	INITRG	Read:	0	REG14	REG13	REG12	REG11	0	0	0
		Write:								

\$0040 - \$007F**ECT (Enhanced Capture Timer 16 Bit 8 Channels)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$007C	TC2H (hi)	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
\$007D	TC2H (lo)	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
\$007E	TC3H (hi)	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
\$007F	TC3H (lo)	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								

\$0080 - \$009F**ATD0 (Analog to Digital Converter 10 Bit 8 Channel)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0080	ATD0CTL0	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0081	ATD0CTL1	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0082	ATD0CTL2	Read:	ADPU	AFFC	AWAI	ETRIGLE	ETRIGP	ETRIG	ASCIE	ASCIF
		Write:								
\$0083	ATD0CTL3	Read:	0	S8C	S4C	S2C	S1C	FIFO	FRZ1	FRZ0
		Write:								
\$0084	ATD0CTL4	Read:	SRES8	SMP1	SMP0	PRS4	PRS3	PRS2	PRS1	PRS0
		Write:								
\$0085	ATD0CTL5	Read:	DJM	DSGN	SCAN	MULT	0	CC	CB	CA
		Write:								
\$0086	ATD0STAT0	Read:	SCF	0	ETORF	FIFOR	0	CC2	CC1	CC0
		Write:								
\$0087	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0088	ATD0TEST0	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0089	ATD0TEST1	Read:	0	0	0	0	0	0	0	SC
		Write:								
\$008A	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$008B	ATD0STAT1	Read:	CCF7	CCF6	CCF5	CCF4	CCF3	CCF2	CCF1	CCF0
		Write:								
\$008C	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$008D	ATD0DIEN	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
\$008E	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$008F	PORTAD0	Read:	Bit7	6	5	4	3	2	1	BIT 0
		Write:								
\$0090	ATD0DR0H	Read:	Bit15	14	13	12	11	10	9	Bit8
		Write:								
\$0091	ATD0DR0L	Read:	Bit7	Bit6	0	0	0	0	0	0
		Write:								

\$00D0 - \$00D7**SCI1 (Asynchronous Serial Interface)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$00D5	SCI1SR2	Read:	0	0	0	0	0	BRK13	TXDIR	RAF
		Write:								
\$00D6	SCI1DRH	Read:	R8	T8	0	0	0	0	0	0
		Write:								
\$00D7	SCI1DRL	Read:	R7	R6	R5	R4	R3	R2	R1	R0
		Write:	T7	T6	T5	T4	T3	T2	T1	T0

\$00D8 - \$00DF**SPI0 (Serial Peripheral Interface)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$00D8	SPI0CR1	Read:	SPIE	SPE	SPTIE	MSTR	CPOL	CPHA	SSOE	LSBFE
		Write:								
\$00D9	SPI0CR2	Read:	0	0	0	MODFEN	BIDIROE	0	SPISWAI	SPC0
		Write:								
\$00DA	SPI0BR	Read:	0	SPPR2	SPPR1	SPPR0	0	SPR2	SPR1	SPR0
		Write:								
\$00DB	SPI0SR	Read:	SPIF	0	SPTEF	MODF	0	0	0	0
		Write:								
\$00DC	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$00DD	SPI0DR	Read:	Bit7	6	5	4	3	2	1	Bit0
		Write:								
\$00DE	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$00DF	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

\$00E0 - \$00E7**IIC (Inter IC Bus)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$00E0	IBAD	Read:	ADR7	ADR6	ADR5	ADR4	ADR3	ADR2	ADR1	0
		Write:								
\$00E1	IBFD	Read:	IBC7	IBC6	IBC5	IBC4	IBC3	IBC2	IBC1	IBC0
		Write:								
\$00E2	IBCR	Read:	IBEN	IBIE	MS/SL	TX/RX	TXAK	0	0	IBSWAI
		Write:						RSTA		
\$00E3	IBSR	Read:	TCF	IAAS	IBB	IBAL	0	SRW	IBIF	RXAK
		Write:								
\$00E4	IBDR	Read:	D7	D6	D5	D4	D3	D2	D1	D0
		Write:								
\$00E5	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$00E6	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$00E7	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

\$0240 - \$027F**PIM (Port Integration Module)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$024A	DDRS	Read: Write:	DDRS7	DDRS7	DDRS5	DDRS4	DDRS3	DDRS2	DDRS1	DDRS0
\$024B	RDRS	Read: Write:	RDRS7	RDRS6	RDRS5	RDRS4	RDRS3	RDRS2	RDRS1	RDRS0
\$024C	PERS	Read: Write:	PERS7	PERS6	PERS5	PERS4	PERS3	PERS2	PERS1	PERS0
\$024D	PPSS	Read: Write:	PPSS7	PPSS6	PPSS5	PPSS4	PPSS3	PPSS2	PPSS1	PPSS0
\$024E	WOMS	Read: Write:	WOMS7	WOMS6	WOMS5	WOMS4	WOMS3	WOMS2	WOMS1	WOMS0
\$024F	Reserved	Read: Write:	0	0	0	0	0	0	0	0
\$0250	PTM	Read: Write:	PTM7	PTM6	PTM5	PTM4	PTM3	PTM2	PTM1	PTM0
\$0251	PTIM	Read: Write:	PTIM7	PTIM6	PTIM5	PTIM4	PTIM3	PTIM2	PTIM1	PTIM0
\$0252	DDRM	Read: Write:	DDRM7	DDRM7	DDRM5	DDRM4	DDRM3	DDRM2	DDRM1	DDRM0
\$0253	RDRM	Read: Write:	RDRM7	RDRM6	RDRM5	RDRM4	RDRM3	RDRM2	RDRM1	RDRM0
\$0254	PERM	Read: Write:	PERM7	PERM6	PERM5	PERM4	PERM3	PERM2	PERM1	PERM0
\$0255	PPSM	Read: Write:	PPSM7	PPSM6	PPSM5	PPSM4	PPSM3	PPSM2	PPSM1	PPSM0
\$0256	WOMM	Read: Write:	WOMM7	WOMM6	WOMM5	WOMM4	WOMM3	WOMM2	WOMM1	WOMM0
\$0257	MODRR	Read: Write:	0	0	0	MODRR4	0	0	MODRR1	MODRR0
\$0258	PTP	Read: Write:	PTP7	PTP6	PTP5	PTP4	PTP3	PTP2	PTP1	PTP0
\$0259	PTIP	Read: Write:	PTIP7	PTIP6	PTIP5	PTIP4	PTIP3	PTIP2	PTIP1	PTIP0
\$025A	DDRP	Read: Write:	DDRP7	DDRP7	DDRP5	DDRP4	DDRP3	DDRP2	DDRP1	DDRP0
\$025B	RDRP	Read: Write:	RDRP7	RDRP6	RDRP5	RDRP4	RDRP3	RDRP2	RDRP1	RDRP0
\$025C	PERP	Read: Write:	PERP7	PERP6	PERP5	PERP4	PERP3	PERP2	PERP1	PERP0
\$025D	PPSP	Read: Write:	PPSP7	PPSP6	PPSP5	PPSP4	PPSP3	PPSP2	PPSP1	PPSS0
\$025E	PIEP	Read: Write:	PIEP7	PIEP6	PIEP5	PIEP4	PIEP3	PIEP2	PIEP1	PIEP0
\$025F	PIFP	Read: Write:	PIFP7	PIFP6	PIFP5	PIFP4	PIFP3	PIFP2	PIFP1	PIFP0
\$0260	PTH	Read: Write:	PTH7	PTH6	PTH5	PTH4	PTH3	PTH2	PTH1	PTH0
\$0261	PTIH	Read: Write:	PTIH7	PTIH6	PTIH5	PTIH4	PTIH3	PTIH2	PTIH1	PTIH0
\$0262	DDRH	Read: Write:	DDRH7	DDRH7	DDRH5	DDRH4	DDRH3	DDRH2	DDRH1	DDRH0

2.3.14 PE6 / MODB / IPIPE1 — Port E I/O Pin 6

PE6 is a general purpose input or output pin. It is used as a MCU operating mode select pin during reset. The state of this pin is latched to the MODB bit at the rising edge of $\overline{\text{RESET}}$. This pin is shared with the instruction queue tracking signal IPIPE1. This pin is an input with a pull-down device which is only active when $\overline{\text{RESET}}$ is low.

2.3.15 PE5 / MODA / IPIPE0 — Port E I/O Pin 5

PE5 is a general purpose input or output pin. It is used as a MCU operating mode select pin during reset. The state of this pin is latched to the MODA bit at the rising edge of $\overline{\text{RESET}}$. This pin is shared with the instruction queue tracking signal IPIPE0. This pin is an input with a pull-down device which is only active when $\overline{\text{RESET}}$ is low.

2.3.16 PE4 / ECLK — Port E I/O Pin 4

PE4 is a general purpose input or output pin. It can be configured to drive the internal bus clock ECLK. ECLK can be used as a timing reference.

2.3.17 PE3 / $\overline{\text{LSTRB}}$ / $\overline{\text{TAGLO}}$ — Port E I/O Pin 3

PE3 is a general purpose input or output pin. In MCU expanded modes of operation, $\overline{\text{LSTRB}}$ can be used for the low-byte strobe function to indicate the type of bus access and when instruction tagging is on, $\overline{\text{TAGLO}}$ is used to tag the low half of the instruction word being read into the instruction queue.

2.3.18 PE2 / $\overline{\text{R/W}}$ — Port E I/O Pin 2

PE2 is a general purpose input or output pin. In MCU expanded modes of operations, this pin drives the read/write output signal for the external bus. It indicates the direction of data on the external bus.

2.3.19 PE1 / $\overline{\text{IRQ}}$ — Port E Input Pin 1

PE1 is a general purpose input pin and the maskable interrupt request input that provides a means of applying asynchronous interrupt requests. This will wake up the MCU from STOP or WAIT mode.

2.3.20 PE0 / $\overline{\text{XIRQ}}$ — Port E Input Pin 0

PE0 is a general purpose input pin and the non-maskable interrupt request input that provides a means of applying asynchronous interrupt requests. This will wake up the MCU from STOP or WAIT mode.

2.3.21 PH7 / KWH7 — Port H I/O Pin 7

PH7 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode.

Mnemonic	Pin Number	Nominal Voltage	Description
	112-pin QFP		
VDDPLL	43	2.5V	Provides operating voltage and ground for the Phased-Locked Loop. This allows the supply voltage to the PLL to be bypassed independently. Internal power and ground generated by internal regulator.
VSSPLL	45	0V	
VREGEN	97	5.0V	Internal Voltage Regulator enable/disable

2.4.1 VDDX, VSSX — Power & Ground Pins for I/O Drivers

External power and ground for I/O drivers. Because fast signal transitions place high, short-duration current demands on the power supply, use bypass capacitors with high-frequency characteristics and place them as close to the MCU as possible. Bypass requirements depend on how heavily the MCU pins are loaded.

VDDX and VSSX are the supplies for Ports J, K, M, P, T and S.

2.4.2 VDDR, VSSR — Power & Ground Pins for I/O Drivers & for Internal Voltage Regulator

External power and ground for I/O drivers and input to the internal voltage regulator. Because fast signal transitions place high, short-duration current demands on the power supply, use bypass capacitors with high-frequency characteristics and place them as close to the MCU as possible. Bypass requirements depend on how heavily the MCU pins are loaded.

VDDR and VSSR are the supplies for Ports A, B, E and H.

2.4.3 VDD1, VDD2, VSS1, VSS2 — Internal Logic Power Supply Pins

Power is supplied to the MCU through VDD and VSS. Because fast signal transitions place high, short-duration current demands on the power supply, use bypass capacitors with high-frequency characteristics and place them as close to the MCU as possible. This 2.5V supply is derived from the internal voltage regulator. There is no static load on those pins allowed. The internal voltage regulator is turned off, if VREGEN is tied to ground.

NOTE: *No load allowed except for bypass capacitors.*

2.4.4 VDDA, VSSA — Power Supply Pins for ATD0/ATD1 and VREG

VDDA, VSSA are the power supply and ground input pins for the voltage regulator and the two analog to digital converters. It also provides the reference for the internal voltage regulator. This allows the supply voltage to ATD0/ATD1 and the reference voltage to be bypassed independently.

4.3.2.2 Executing from External Memory

The user may wish to execute from external space with a secured microcontroller. This is accomplished by resetting directly into expanded mode. The internal FLASH and EEPROM will be disabled. BDM operations will be blocked.

4.3.3 Unsecuring the Microcontroller

In order to unsecure the microcontroller, the internal FLASH and EEPROM must be erased. This can be done through an external program in expanded mode or via a sequence of BDM commands. Unsecuring is also possible via the Backdoor Key Access. Refer to Flash Block Guide for details.

Once the user has erased the FLASH and EEPROM, the part can be reset into special single chip mode. This invokes a program that verifies the erasure of the internal FLASH and EEPROM. Once this program completes, the user can erase and program the FLASH security bits to the unsecured state. This is generally done through the BDM, but the user could also change to expanded mode (by writing the mode bits through the BDM) and jumping to an external program (again through BDM commands). Note that if the part goes through a reset before the security bits are reprogrammed to the unsecure state, the part will be secured again.

4.4 Low Power Modes

The microcontroller features three main low power modes. Consult the respective Block User Guide for information on the module behavior in Stop, Pseudo Stop, and Wait Mode. An important source of information about the clock system is the Clock and Reset Generator User Guide (CRG).

4.4.1 Stop

Executing the CPU STOP instruction stops all clocks and the oscillator thus putting the chip in fully static mode. Wake up from this mode can be done via reset or external interrupts.

4.4.2 Pseudo Stop

This mode is entered by executing the CPU STOP instruction. In this mode the oscillator is still running and the Real Time Interrupt (RTI) or Watchdog (COP) sub module can stay active. Other peripherals are turned off. This mode consumes more current than the full STOP mode, but the wake up time from this mode is significantly shorter.

4.4.3 Wait

This mode is entered by executing the CPU WAI instruction. In this mode the CPU will not execute instructions. The internal CPU signals (address and data bus) will be fully static. All peripherals stay active. For further power consumption the peripherals can individually turn off their local clocks.

4.4.4 Run

Although this is not a low power mode, unused peripheral modules should not be enabled in order to save power.

Consult the FTS64K Block User Guide for information about the flash module.

The "S12 LRAE" is a generic Load RAM and Execute (LRAE) program which will be programmed into the flash memory of this device during manufacture. This LRAE program will provide greater programming flexibility to the end users by allowing the device to be programmed directly using CAN or SCI after it is assembled on the PCB. Use of the LRAE program is at the discretion of the end user and, if not required, it must simply be erased prior to flash programming. For more details of the S12 LRAE and its implementation, please see the S12 LREA Application Note (AN2546/D).

It is planned that most HC9S12 devices manufactured after Q1 of 2004 will be shipped with the S12 LRAE programmed in the Flash . Exact details of the changeover (ie blank to programmed) for each product will be communicated in advance via GPCN and will be traceable by the customer via datecode marking on the device.

Please contact Freescale SPS Sales if you have any additional questions.

Section 17 EEPROM 1K Block Description

Consult the EETS1K Block User Guide for information about the EEPROM module.

Section 18 RAM Block Description

This module supports single-cycle misaligned word accesses.

Section 19 MSCAN Block Description

Consult the MSCAN Block User Guide for information about the Freescale Scalable CAN Module.

Section 20 Port Integration Module (PIM) Block Description

Consult the PIM_9DJ64 Block User Guide for information about the Port Integration Module.

Section 21 Voltage Regulator (VREG) Block Description

Consult the VREG Block User Guide for information about the dual output linear voltage regulator.

Section 22 Printed Circuit Board Layout Proposals

Figure 22-1 Recommended PCB Layout 112LQFP Colpitts Oscillator

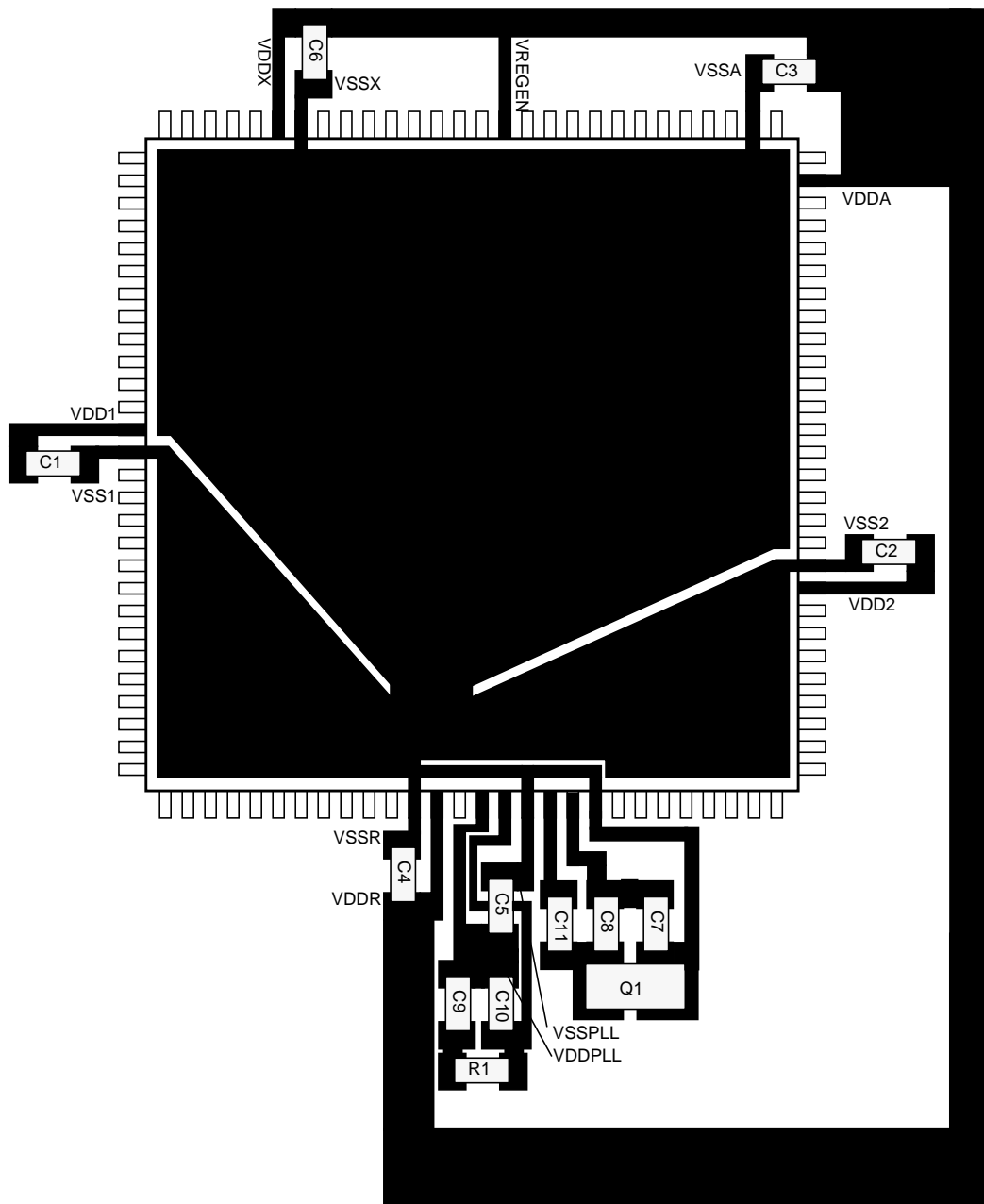
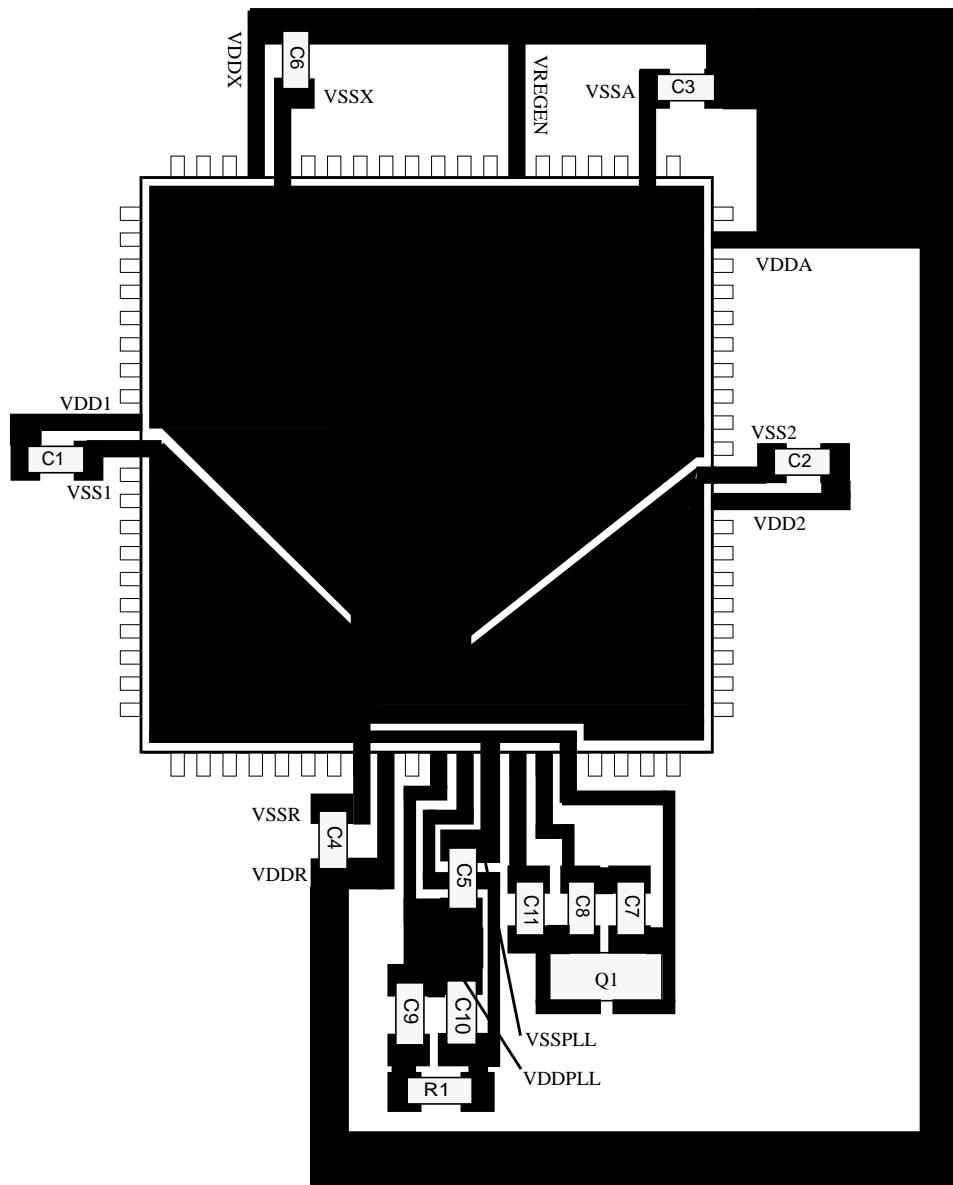


Figure 22-2 Recommended PCB Layout for 80QFP Colpitts Oscillator



T_A = Ambient Temperature, [°C]

P_D = Total Chip Power Dissipation, [W]

Θ_{JA} = Package Thermal Resistance, [°C/W]

The total power dissipation can be calculated from:

$$P_D = P_{INT} + P_{IO}$$

P_{INT} = Chip Internal Power Dissipation, [W]

Two cases with internal voltage regulator enabled and disabled must be considered:

1. Internal Voltage Regulator disabled

$$P_{INT} = I_{DD} \cdot V_{DD} + I_{DDPLL} \cdot V_{DDPLL} + I_{DDA} \cdot V_{DDA}$$

$$P_{IO} = \sum_i R_{DS(on)} \cdot I_{IO_i}^2$$

P_{IO} is the sum of all output currents on I/O ports associated with VDDX and VDDR.

For $R_{DS(on)}$ is valid:

$$R_{DS(on)} = \frac{V_{OL}}{I_{OL}}; \text{for outputs driven low}$$

respectively

$$R_{DS(on)} = \frac{V_{DD5} - V_{OH}}{I_{OH}}; \text{for outputs driven high}$$

2. Internal voltage regulator enabled

$$P_{INT} = I_{DDR} \cdot V_{DDR} + I_{DDA} \cdot V_{DDA}$$

I_{DDR} is the current shown in **Table A-7** and not the overall current flowing into VDDR, which additionally contains the current flowing into the external loads with output high.

$$P_{IO} = \sum_i R_{DS(on)} \cdot I_{IO_i}^2$$

P_{IO} is the sum of all output currents on I/O ports associated with VDDX and VDDR.

A.2 ATD Characteristics

This section describes the characteristics of the analog to digital converter.

A.2.1 ATD Operating Characteristics

The **Table A-8** shows conditions under which the ATD operates.

The following constraints exist to obtain full-scale, full range results:

$V_{SSA} \leq V_{RL} \leq V_{IN} \leq V_{RH} \leq V_{DDA}$. This constraint exists since the sample buffer amplifier can not drive beyond the power supply levels that it ties to. If the input level goes outside of this range it will effectively be clipped.

Table A-8 ATD Operating Characteristics

Conditions are shown in Table A-4 unless otherwise noted							
Num	C	Rating	Symbol	Min	Typ	Max	Unit
1	D	Reference Potential Low High	V_{RL} V_{RH}	V_{SSA} $V_{DDA}/2$		$V_{DDA}/2$ V_{DDA}	V V
2	C	Differential Reference Voltage ¹	$V_{RH}-V_{RL}$	4.50	5.00	5.25	V
3	D	ATD Clock Frequency	f_{ATDCLK}	0.5		2.0	MHz
4	D	ATD 10-Bit Conversion Period Clock Cycles ² Conv, Time at 2.0MHz ATD Clock f_{ATDCLK}	N_{CONV10} T_{CONV10}	14 7		28 14	Cycles μs
5	D	ATD 8-Bit Conversion Period Clock Cycles ² Conv, Time at 2.0MHz ATD Clock f_{ATDCLK}	N_{CONV8} T_{CONV8}	12 6		26 13	Cycles μs
6	D	Recovery Time ($V_{DDA}=5.0$ Volts)	t_{REC}			20	μs
7	P	Reference Supply current 2 ATD blocks on	I_{REF}			0.750	mA
8	P	Reference Supply current 1 ATD block on	I_{REF}			0.375	mA

NOTES:

1. Full accuracy is not guaranteed when differential voltage is less than 4.50V
2. The minimum time assumes a final sample period of 2 ATD clocks cycles while the maximum time assumes a final sample period of 16 ATD clocks.

A.2.2 Factors influencing accuracy

Three factors - source resistance, source capacitance and current injection - have an influence on the accuracy of the ATD.

A.2.2.1 Source Resistance:

Due to the input pin leakage current as specified in **Table A-6** in conjunction with the source resistance there will be a voltage drop from the signal source to the ATD input. The maximum source resistance R_S

Table A-20 Expanded Bus Timing Characteristics

Conditions are shown in Table A-4 unless otherwise noted, $C_{LOAD} = 50pF$							
Num	C	Rating	Symbol	Min	Typ	Max	Unit
32	D	NOACC hold time	t_{NOH}	2			ns
33	D	IPIPO[1:0] delay time	t_{P0D}	2		7	ns
34	D	IPIPO[1:0] valid time to E rise ($PW_{EL} - t_{P0D}$)	t_{P0V}	11			ns
35	D	IPIPO[1:0] delay time ¹ ($PW_{EH} - t_{P1V}$)	t_{P1D}	2		25	ns
36	D	IPIPO[1:0] valid time to E fall	t_{P1V}	11			ns

NOTES:

1. Affected by clock stretch: add $N \times t_{cyc}$ where $N=0,1,2$ or 3, depending on the number of clock stretches.

User Guide End Sheet